

# Per-Erik Tegehall

## List of Publications by Year in descending order

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17  
papers

257  
citations

1163117

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1372567

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17  
docs citations

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times ranked

190  
citing authors

#	ARTICLE	IF	CITATIONS
1	Transgranular Crack Propagation in Thermal Cycling of SnAgCu Solder Joints. , 2019, , .		2
2	Effect of PCB cracks on thermal cycling reliability of passive microelectronic components with single-grained solder joints. Microelectronics Reliability, 2019, 93, 61-71.	1.7	23
3	The Stress State of BGA Solder Joints Influenced by the Grain Orientations of Neighboring Joints. , 2018, , .		5
4	On the formation and propagation of laminate cracks and their influence on the fatigue lives of solder joints. , 2018, , .		3
5	Simulations of the impact of single-grained lead-free solder joints on the reliability of ball Grid Array components. , 2017, , .		8
6	Impact of laminate cracks under solder pads on the fatigue lives of ball grid array solder joints. Microelectronics Reliability, 2015, 55, 2354-2370.	1.7	13
7	Thermo-mechanical simulations and measurements on high temperature interconnections. , 2011, , .		1
8	Reliability of Microtechnology. , 2011, , .		19
9	Thermal Cycling Aging Effect on the Shear Strength, Microstructure, Intermetallic Compounds (IMC) and Crack Initiation and Propagation of Reflow Soldered Sn-3.8Ag-0.7Cu and Wave Soldered Sn-3.5Ag Ceramic Chip Components. IEEE Transactions on Components and Packaging Technologies, 2008, 31, 331-344.	1.3	21
10	Printed circuit boards for lead-free soldering: materials and failure mechanisms. Circuit World, 2007, 33, 10-16.	0.9	4
11	Effect of different temperature cycling profiles on the crack initiation and propagation of Sn-3.5Ag wave soldered solder joints. Microelectronics Reliability, 2007, 47, 266-272.	1.7	1
12	Evolution of Intermetallic Compounds in PBGA Sn-Ag-Cu Solder Joints during Thermal Cycling Testing. , 2006, , .		1
13	Nucleation and formation of zinc phosphate conversion coating on cold-rolled steel. Corrosion Science, 1991, 32, 635-652.	6.6	57
14	The mechanism of chemical activation with titanium phosphate colloids in the formation of zinc phosphate conversion coatings. Colloids and Surfaces, 1990, 49, 373-383.	0.9	37
15	Colloidal titanium phosphate, the chemical activator in surface conditioning before zinc phosphating. Colloids and Surfaces, 1989, 42, 155-164.	0.9	27
16	Ion Exchange on alpha-Titanium Phosphate and Formation of New Crystalline Phases by Hydrolysis of the Ion-Exchanged Phases.. Acta Chemica Scandinavica, 1989, 43, 322-330.	0.7	13
17	Synthesis of Crystalline Titanium(IV) Phosphates by Direct Precipitation from Ti(III) Solutions and Ion Exchange Properties of Some of the Prepared Phases.. Acta Chemica Scandinavica, 1986, 40a, 507-514.	0.7	22